## Reference Numeral List

- 10 semiconductor wafer
- 12 region carrying information
- 14 magnetic means, information for identification
- 16 magnetic ions
- 18 magnetic films, magnetic means
- 20 EPI encapsulation
- 22 oxide back seal
- 24 wafer edge
- 26 magnetic sensor
- 28 wafer surface
- 30 wafer surface
- 110 semiconductor wafer
- 200 laser scribe beam
- 210 laser scribe pits
- 212 contamination
- 214 contamination
- 216 contamination